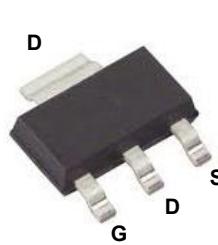
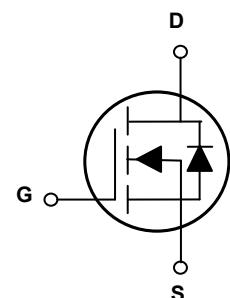


## Main Product Characteristics

$V_{(BR)DSS}$	100V
$R_{DS(ON)}$	185mΩ
$I_D$	3A



SOT-223



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSFL1004 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous( $T_C=25^\circ\text{C}$ )	$I_D$	3	A
Drain Current-Continuous( $T_C=100^\circ\text{C}$ )		1.8	A
Drain Current-Pulsed <sup>1</sup>	$I_{DM}$	12	A
Power Dissipation( $T_C=25^\circ\text{C}$ )	$P_D$	1.78	W
Power Dissipation-Derate Above 25°C		0.014	W/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	70	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	30	°C/W
Storage Temperature Range	$T_{STG}$	-50 To +150	°C
Operating Junction Temperature Range	$T_J$	-50 To +150	°C

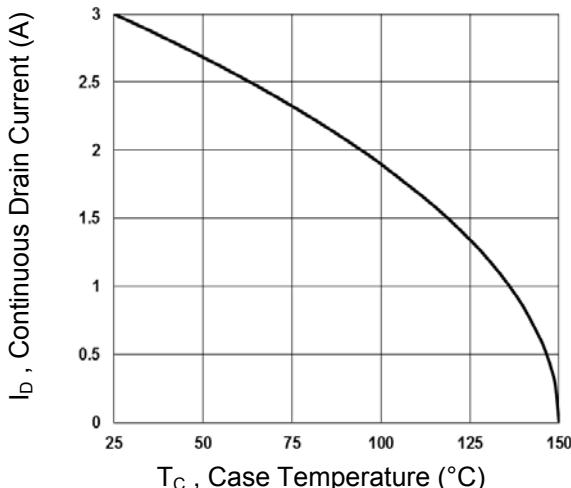
**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	100	-	-	V
$\text{BV}_{\text{DSS}}$ Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=1\text{mA}$	-	0.1	-	$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$V_{\text{DS}}=80\text{V}, V_{\text{GS}}=0\text{V}, T_J=125^\circ\text{C}$	-	-	10	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=2\text{A}$	-	160	185	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=1\text{A}$	-	170	195	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.2	1.8	2.5	V
$V_{\text{GS}(\text{th})}$ Temperature Coefficient	$\Delta V_{\text{GS}(\text{th})}$		-	-4	-	$\text{mV}/^\circ\text{C}$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=1\text{A}$	-	5	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>2,3</sup>	$Q_g$	$V_{\text{DS}}=50\text{V}, I_{\text{D}}=2\text{A}, V_{\text{GS}}=10\text{V}$	-	13.4	21	$\text{nC}$
Gate-Source Charge <sup>2,3</sup>	$Q_{\text{gs}}$		-	2.9	6	
Gate-Drain Charge <sup>2,3</sup>	$Q_{\text{gd}}$		-	1.7	4	
Turn-On Delay Time <sup>2,3</sup>	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=30\text{V}, R_{\text{G}}=3.3\Omega, V_{\text{GS}}=10\text{V}, I_{\text{D}}=1\text{A}$	-	1.6	3	$\text{nS}$
Rise Time <sup>2,3</sup>	$t_r$		-	6.6	13	
Turn-Off Delay Time <sup>2,3</sup>	$t_{\text{d}(\text{off})}$		-	11.5	22	
Fall Time <sup>2,3</sup>	$t_f$		-	3.6	7	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=50\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	820	1190	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		-	35	55	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	20	30	
Gate Resistance	$R_g$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$	-	1.3	2.6	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_s$	$V_G=V_D=0\text{V}, \text{Force Current}$	-	-	3	A
Pulsed Source Current	$I_{\text{SM}}$		-	-	6	A
Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=1\text{A}, T_J=25^\circ\text{C}$	-	-	1	V

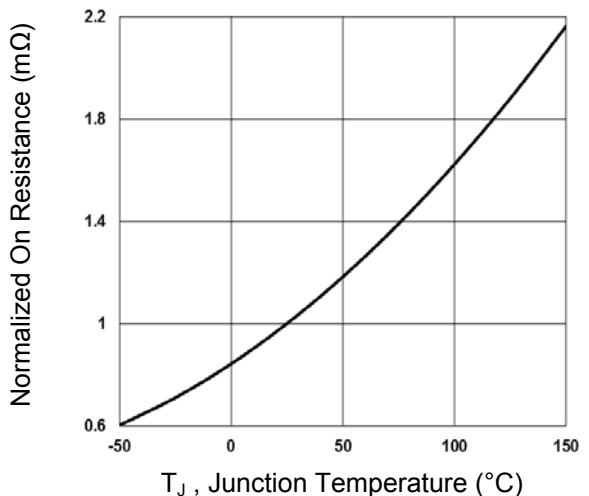
Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

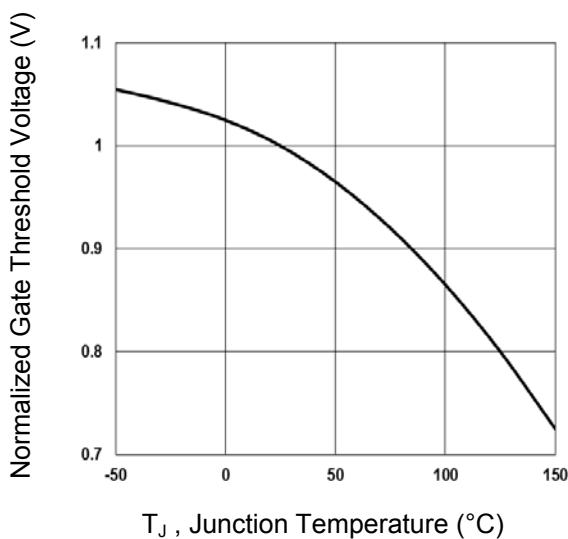
## Typical Electrical and Thermal Characteristic Curves



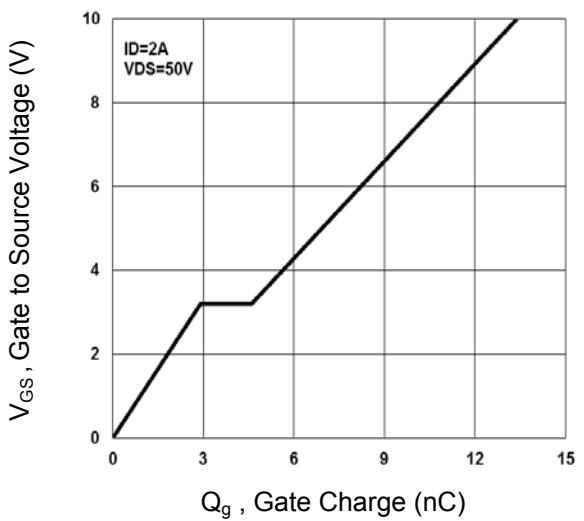
**Fig.1 Continuous Drain Current vs. T<sub>c</sub>**



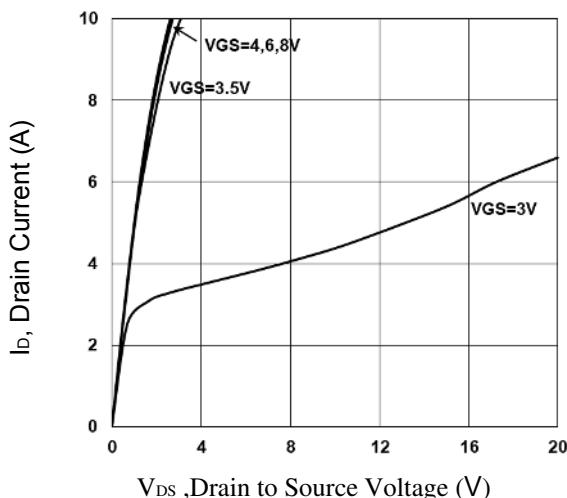
**Fig.2 Normalized R<sub>DS(ON)</sub> vs. T<sub>j</sub>**



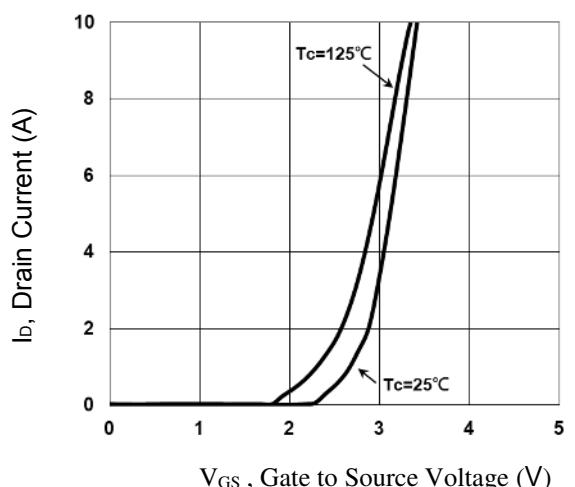
**Fig.3 Normalized V<sub>th</sub> vs. T<sub>j</sub>**



**Fig.4 Gate Charge Waveform**



**Fig.5 Typical Output Characteristics**



**Fig.6 Transfer Characteristics**

## Typical Electrical and Thermal Characteristic Curves

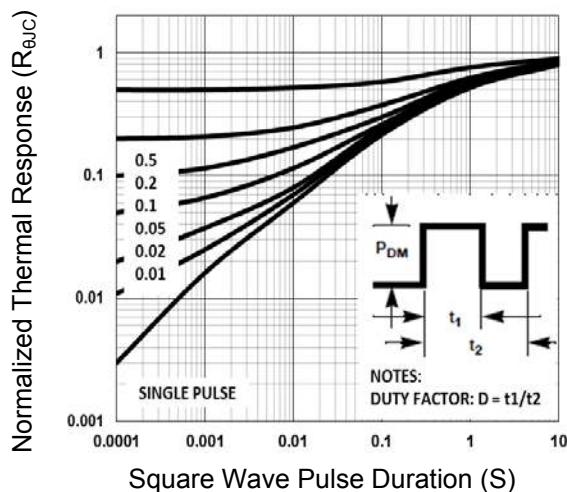


Fig.7 Normalized Transient Impedance

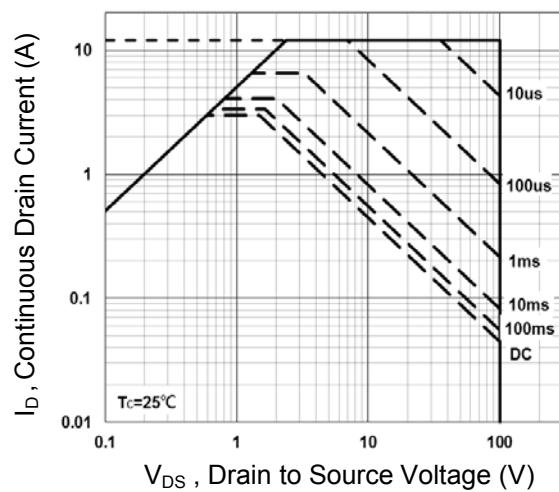


Fig.8 Maximum Safe Operation Area

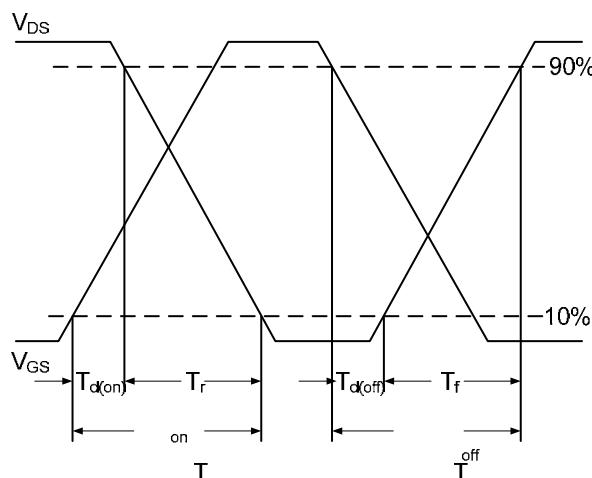


Fig.9 Switching Time Waveform

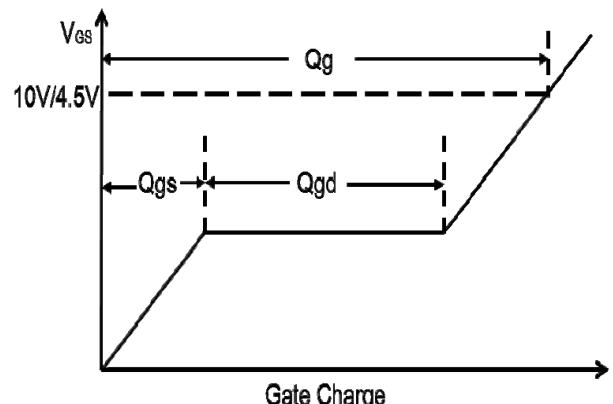
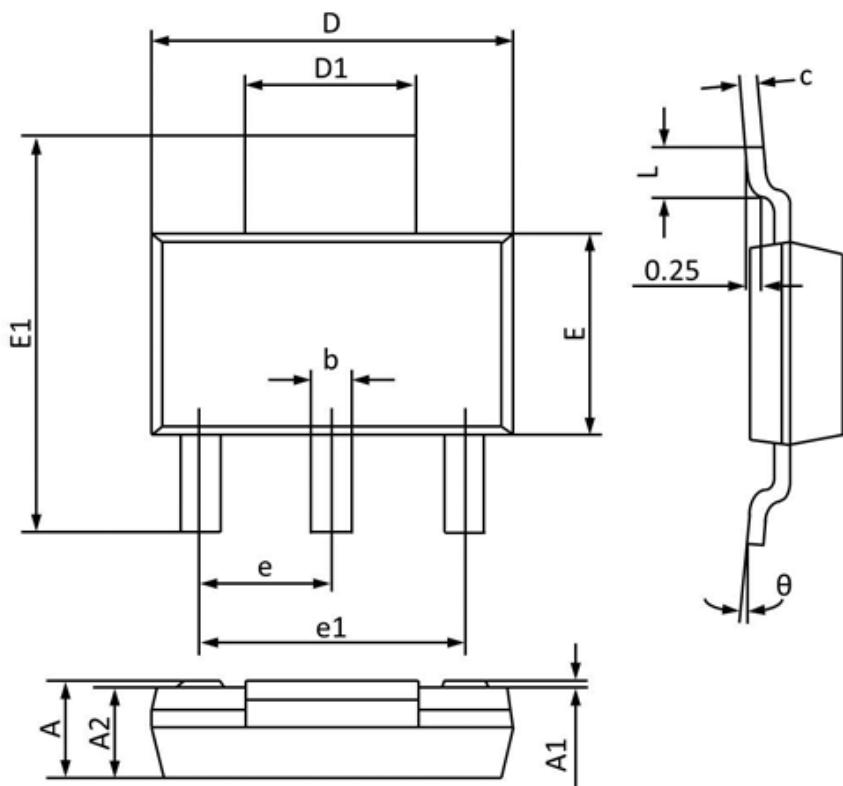


Fig.10 Gate Charge Waveform

### Package Outline Dimensions

SOT-223



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.520	1.800	0.060	0.071
A1	0.000	0.100	0.000	0.004
A2	1.500	1.700	0.059	0.067
b	0.660	0.820	0.026	0.032
c	0.250	0.350	0.010	0.014
D	6.200	6.400	0.244	0.252
D1	2.900	3.100	0.114	0.122
E	3.300	3.700	0.130	0.146
E1	6.830	7.070	0.269	0.278
e	2.300 (BSC)		0.091 (BSC)	
e1	4.500	4.700	0.177	0.185
L	0.900	1.150	0.035	0.045
θ	0°	10°	°0	10°